



STN488DN



N Channel Enhancement Mode MOSFET

100A

DESCRIPTION

STN488DN uses Trench MOSFET technology that is uniquely optimized to provide the most efficient high frequency switching performance. It has been optimized for low gate charge, low $R_{DS(ON)}$ and fast switching speed.

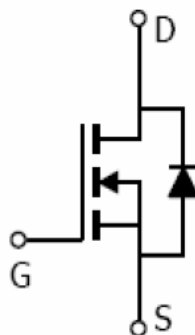
PIN CONFIGURATION POWER PACK 5x6



Y : Year Code
A : Date Code
B : Package Code
C : Process Code

FEATURE

- 40V/25A, $R_{DS(ON)} = 2.2m\Omega$
@ $V_{GS} = 10V$
- 40V/12A, $R_{DS(ON)} = 2.6m\Omega$
@ $V_{GS} = 4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- PPAK5x6 package design





100A

ABSOLUTE MAXIMUM RATINGS (Ta = 25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	VDSS	40	V
Gate-Source Voltage	VGSS	±20	V
Continuous Drain Current (TJ=150°C)	ID	100 63	A
Pulsed Drain Current	IDM	400	A
Continuous Source Current (Diode Conduction)	IS	100	A
Power Dissipation	PD	135	W
Operation Junction Temperature	TJ	150	°C
Storage Temperature Range	TSTG	-55/150	°C
Thermal Resistance-Junction to Ambient	RθJA	62	°C/W



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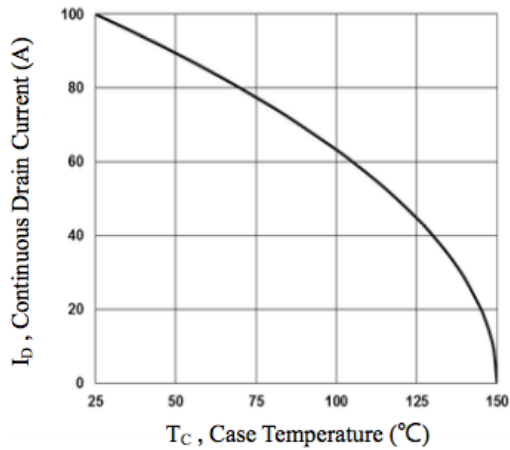
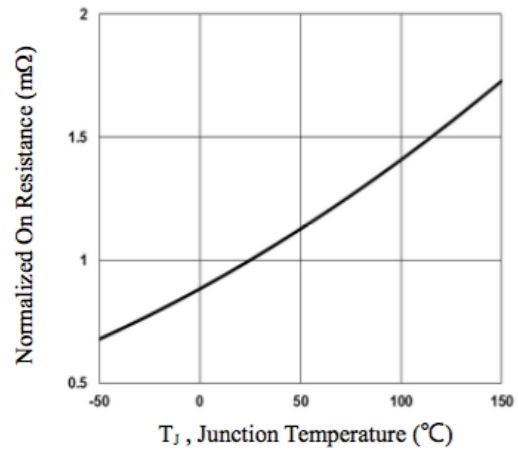
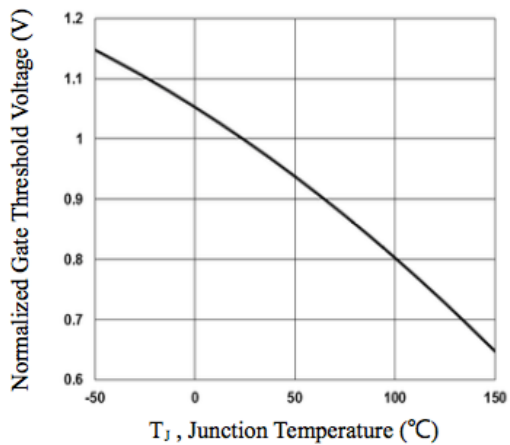
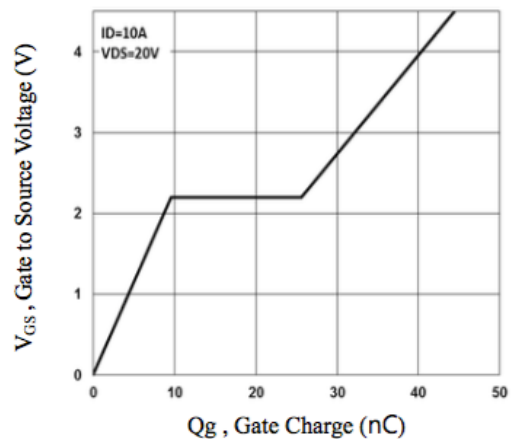
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ELECTRICAL CHARACTERISTICS (Ta = 25°C Unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	40			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0		2.5	V
Gate Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=40V, V_{GS}=0V$			1	uA
		$V_{DS}=32V, V_{GS}=0V$ $T_J=125^{\circ}C$			10	
Drain-source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=25A$ $V_{GS}=4.5V, I_D=12A$		2.2 2.6	2.8 3.5	mΩ
Forward Transconductance	g_{fs}	$V_{DS}=10V, I_D=2A$		16		S
Diode Forward Voltage	V_{SD}	$I_S=1.0A, V_{GS}=0V$			1.0	V
Dynamic						
Total Gate Charge	Q_g	$V_{DS}=20V, V_{GS}=4.5V$ $I_D=10A$		44.4	80	nC
Gate-Source Charge	Q_{gs}			9.6	18	
Gate-Drain Charge	Q_{gd}			16	30	
Input Capacitance	C_{iss}	$V_{DS}=25V, V_{GS}=0V$ $F=1MHz$		4940	7800	pF
Output Capacitance	C_{oss}			420	800	
Reverse TransferCapacitance	C_{rss}			170	330	
Turn-On Time	$t_{d(on)}$ t_r	$V_{DS}=20V, I_D=1A$ $V_{GS}=10V, R_G=6\Omega$		28	50	nS
Turn-Off Time	$t_{d(off)}$ t_f			3.2	6.5	
				105	150	
				40	28	

TYPICAL CHARACTERISTICS

Fig.1 Continuous Drain Current vs. T_c

Fig.2 Normalized $R_{DS(on)}$ vs. T_j

Fig.3 Normalized V_{th} vs. T_j

Fig.4 Gate Charge Waveform

TYPICAL CHARACTERISTICS

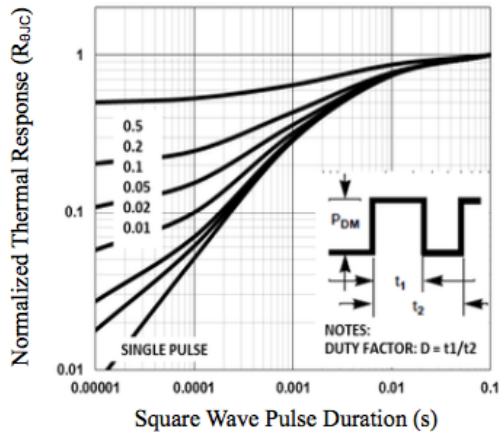


Fig.5 Normalized Transient Impedance

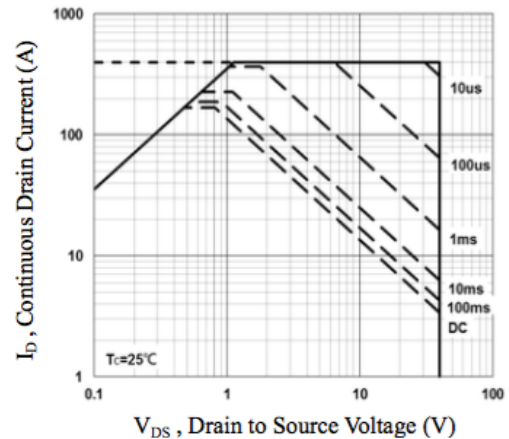


Fig.6 Maximum Safe Operation Area

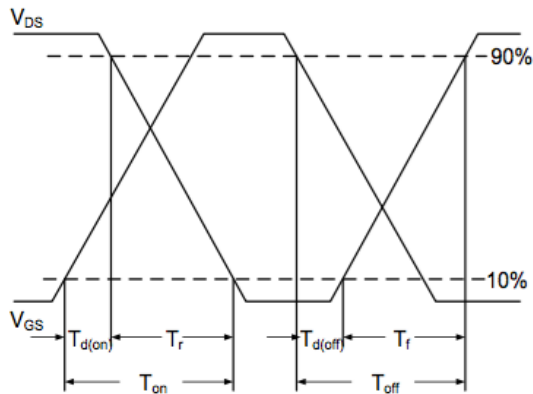


Fig.7 Switching Time Waveform

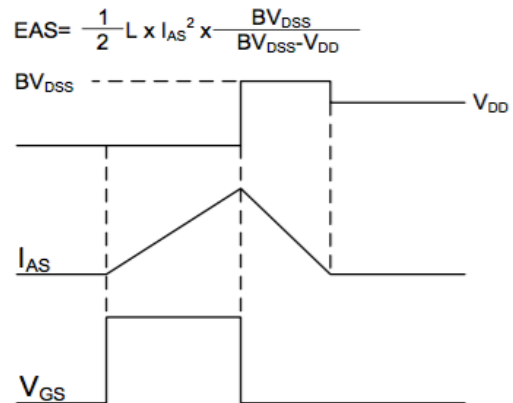
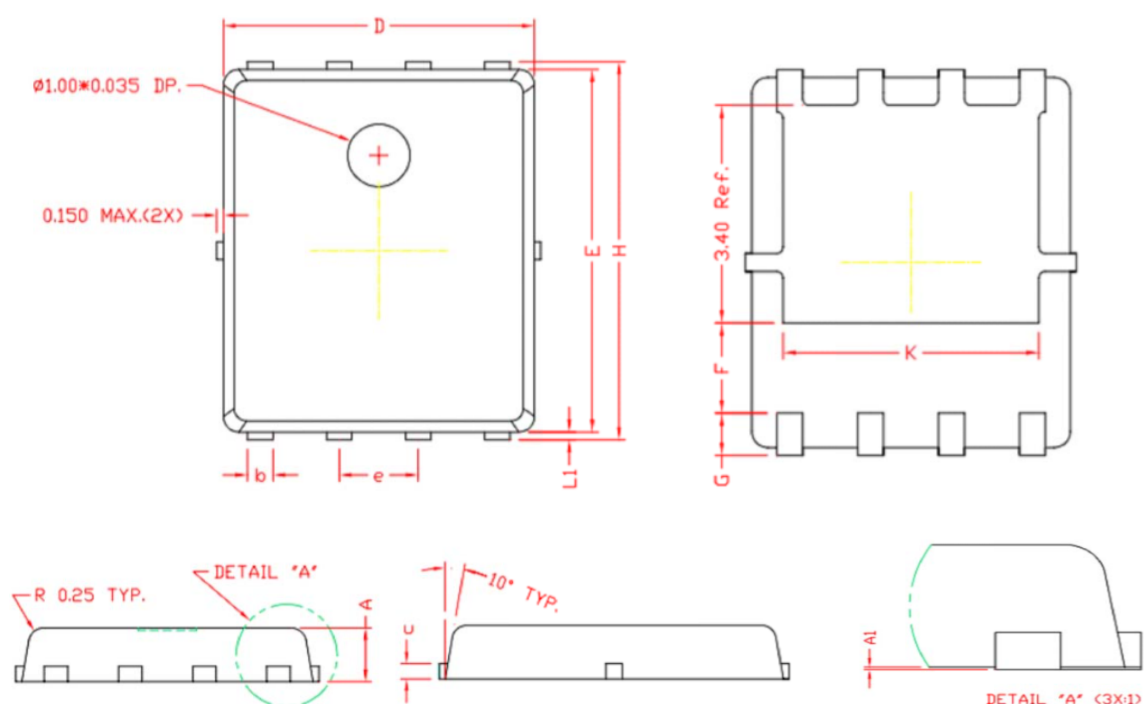


Fig.8 EAS Waveform

POWER PACKAGE 5x6 OUTLINE



(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	0.80	0.90	1.00
A1	0.00	0.03	0.05
b	0.35	0.42	0.49
c	0.254 REF.		
D	4.90	5.00	5.10
F	1.40 REF.		
E	5.70	5.80	5.90
e	1.27 BSC.		
H	5.95	6.08	6.20
L1	0.10	0.14	0.18
G	0.60 REF.		
K	4.00 REF.		